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(12) **United States Design Patent**
Watanabe et al.

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(54) **ELECTRONIC COMPONENT COOLING APPARATUS**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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May 13, 2004	(JP)	2004-014194
May 13, 2004	(JP)	2004-014195

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/179**

(58) **Field of Classification Search** D23/370,
D23/379; D13/179; 165/80.3, 121, 122, 146;
361/274.3, 695, 697, 700, 702, 709
See application file for complete search history.

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Primary Examiner—Lisa Lichtenstein

(74) *Attorney, Agent, or Firm*—Rankin, Hill, Porter & Clark LLP

(57) **CLAIM**

The ornamental design for an electronic component cooling apparatus, as shown and described.

DESCRIPTION

FIG. 1 is a front elevation view of a first embodiment of an electronic component cooling apparatus showing our new design;

FIG. 2 is a rear elevation view of the first embodiment of the cooling apparatus;

FIG. 3 is a right side elevation view of the first embodiment of the cooling apparatus;

FIG. 4 is a left side elevation view of the first embodiment of the cooling apparatus;

FIG. 5 is a top plan view of the first embodiment of the cooling apparatus;

FIG. 6 is a bottom plan view of the first embodiment of the cooling apparatus;

FIG. 7 is a top plan reference view of the first embodiment of the cooling apparatus;

FIG. 8 is a longitudinal cross sectional view of the first embodiment of the cooling apparatus;

FIG. 9 is a perspective view of the first embodiment of the cooling apparatus;

FIG. 10 is a front elevation view of a second embodiment of an electronic component cooling apparatus showing our new design;

FIG. 11 is a rear elevation view of the second embodiment of the cooling apparatus;

FIG. 12 is a right side elevation view of the second embodiment of the cooling apparatus;

FIG. 13 is a left side elevation view of the second embodiment of the cooling apparatus;

FIG. 14 is a top plan view of the second embodiment of the cooling apparatus;

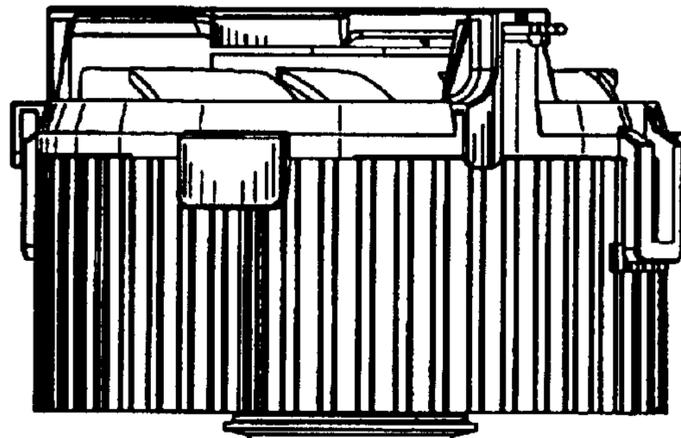
FIG. 15 is a bottom plan view of the second embodiment of the cooling apparatus;

FIG. 16 is a top plan reference view of the second embodiment of the cooling apparatus;

FIG. 17 is a longitudinal cross sectional view of the second embodiment of the cooling apparatus taken along line 17—17 in FIG. 16; and,

FIG. 18 is a perspective view of the third embodiment of the cooling apparatus.

1 Claim, 10 Drawing Sheets



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Fig. 1

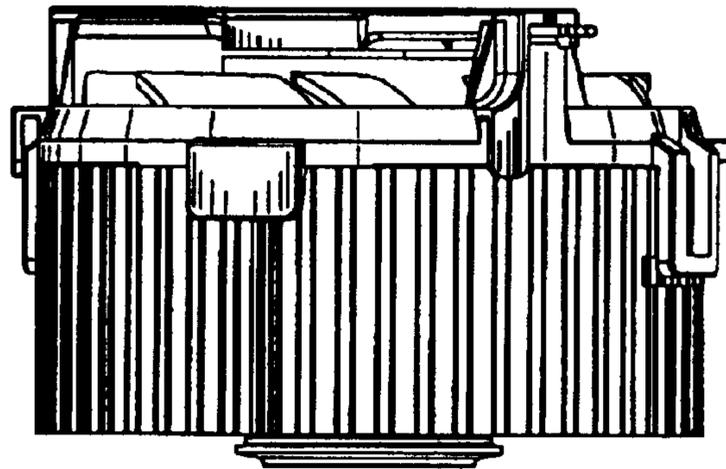


Fig. 2

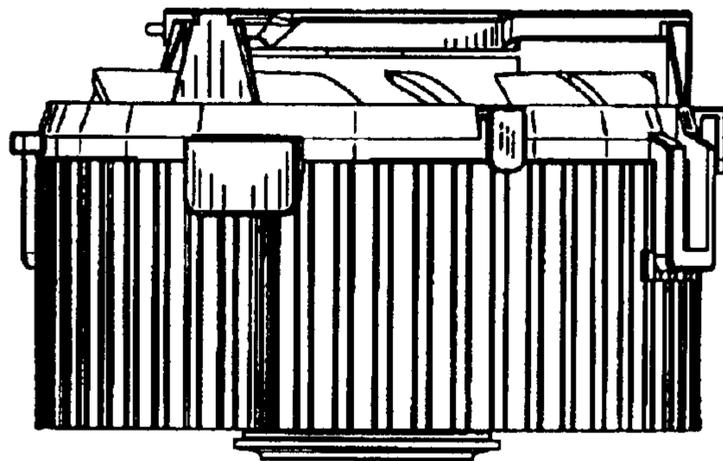


Fig. 3

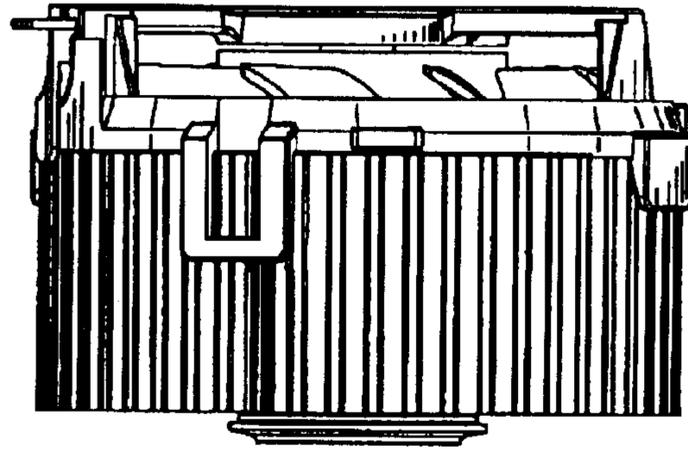


Fig. 4

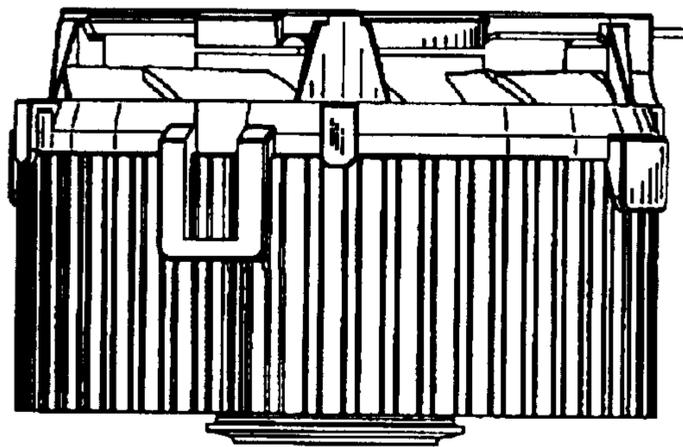


Fig. 5

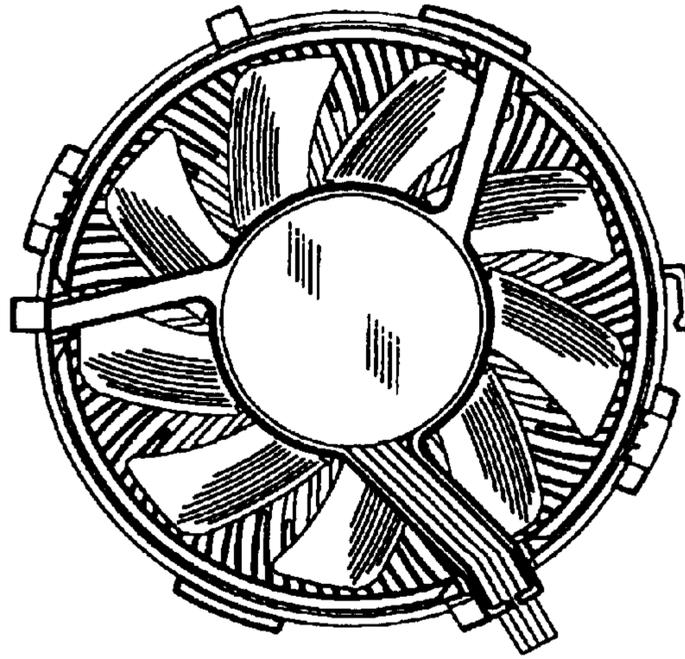


Fig. 6

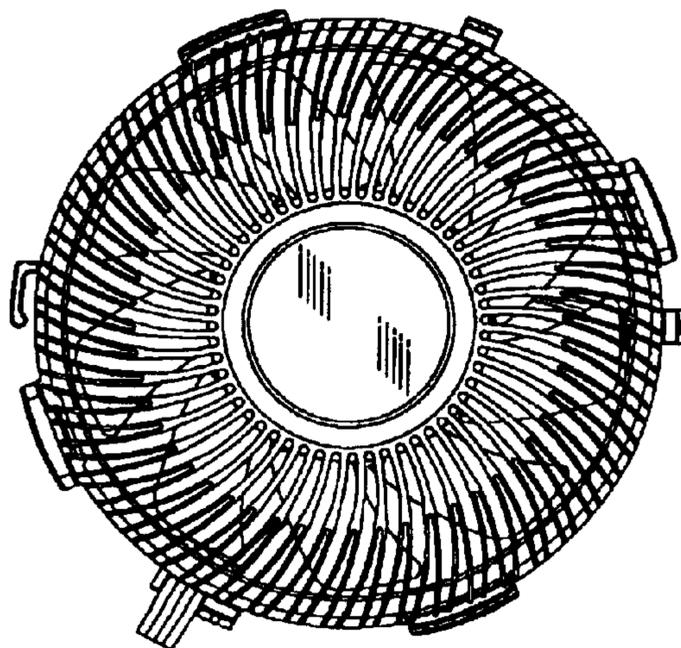


Fig. 7

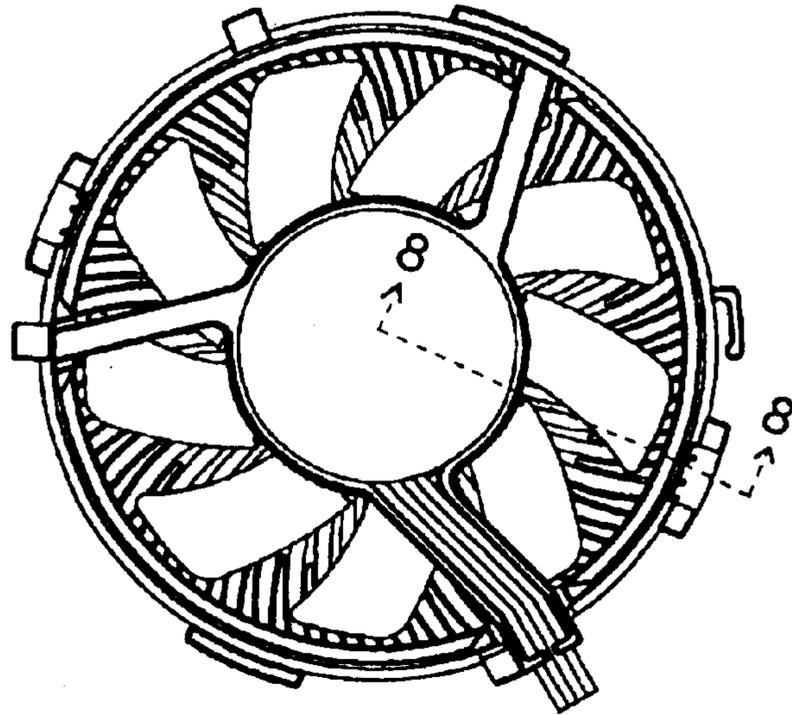


Fig. 8

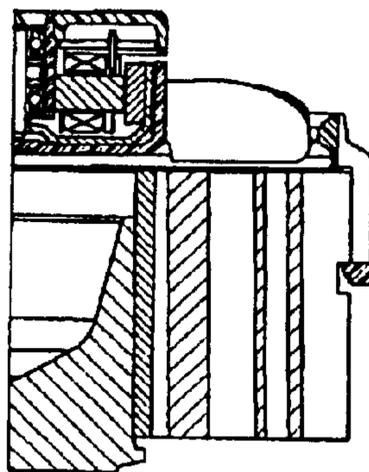


Fig. 9

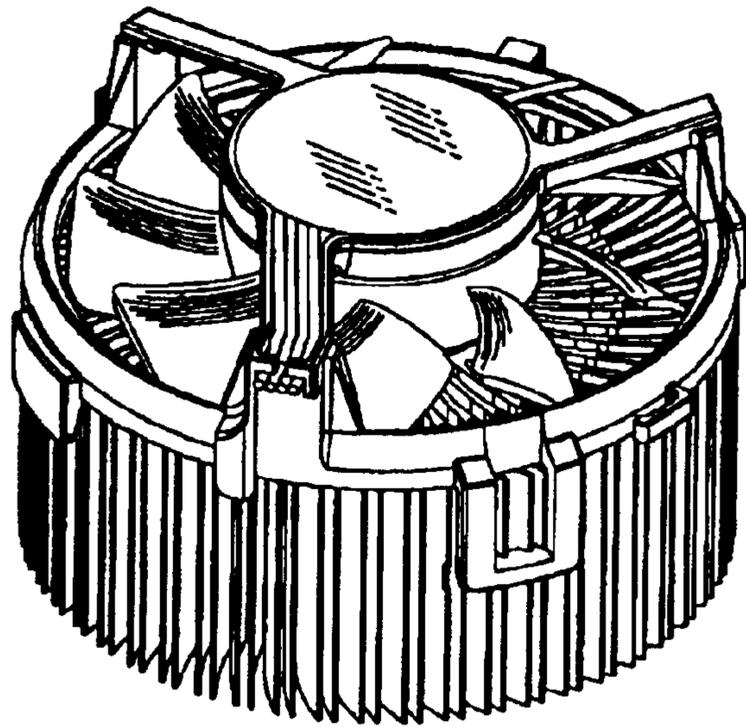


Fig. 10

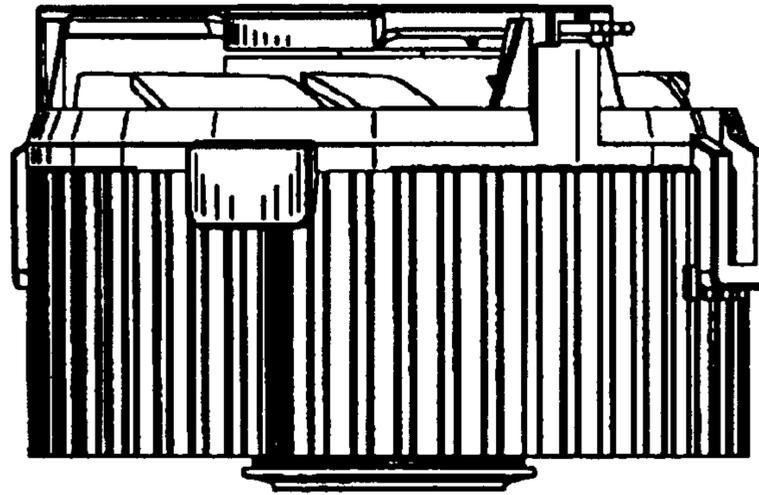


Fig. 11

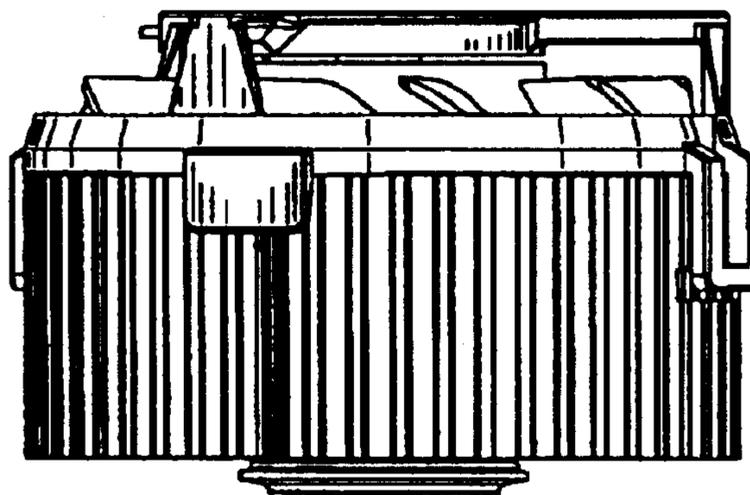


Fig. 12

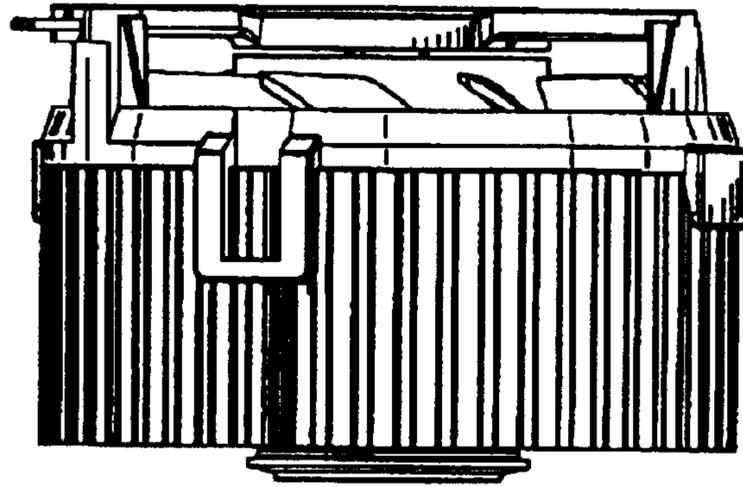


Fig. 13

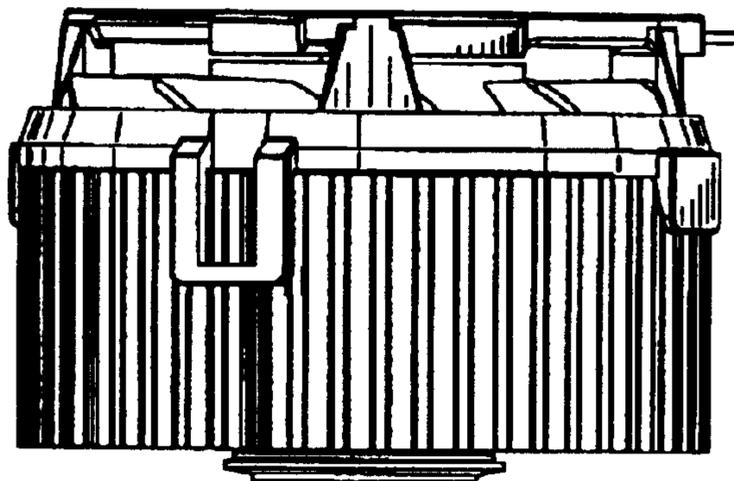


Fig. 14

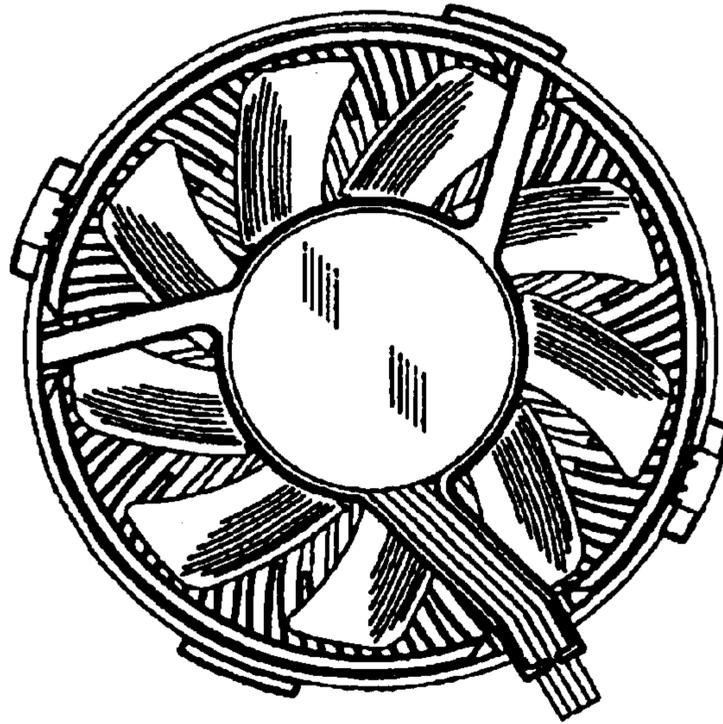


Fig. 15

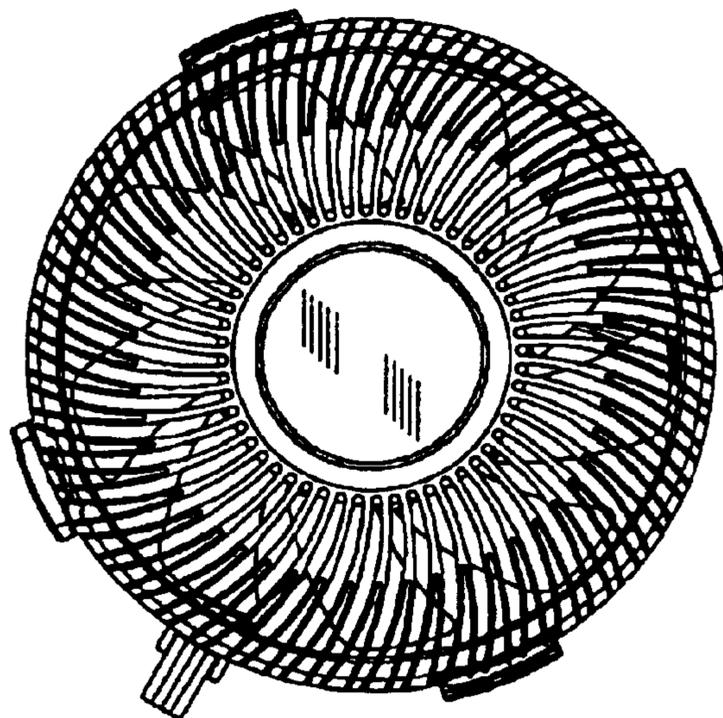


Fig. 16

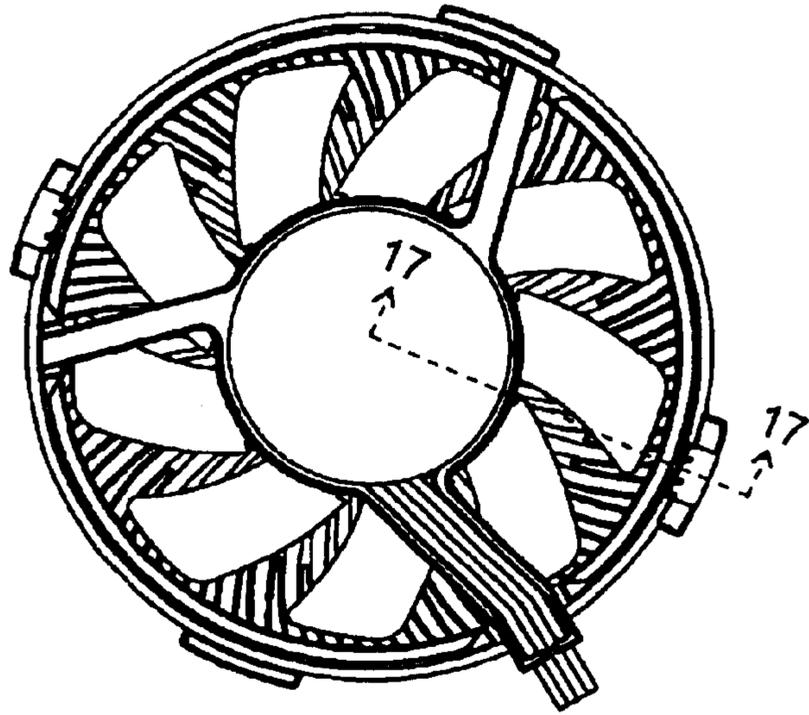


Fig. 17

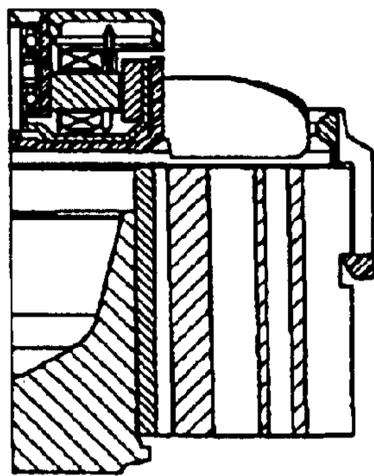


Fig. 18

